

What is claimed is:

1. An integrated package comprising:
 - a first wafer having a first surface;
 - a second wafer having a first surface bonded at a first perimeter to the first surface of the first wafer; and
 - a recess formed in the first surface of the first wafer in a second perimeter situated within the first perimeter.
2. The package of claim 1, further comprising a first bump pattern in the first surface of the first wafer within the second perimeter.
3. The package of claim 2, further comprising a second bump pattern on a second surface of the first wafer.
4. The package of claim 3, further comprising a seal between the first and second wafers at the first perimeter.
5. The package of claim 4, wherein the seal comprises:
 - a spacer material; and

a layer of malleable material.

6. The package of claim 5, wherein the seal further comprises a layer of bondable material.

7. The package of claim 6, further comprising structural supports in the recess of the first wafer.

8. The package of claim 7, further comprising at least one pumpout opening in the first wafer.

9. The package of claim 8, wherein the first and second wafers comprise silicon.

10. A method for making an integrated package, comprising:
providing a first wafer;
making a recess at a first perimeter in a first surface of the first wafer; and
bonding a second wafer to the first wafer with a seal formed at a second perimeter outside the first perimeter.

11. The method of claim 10, further comprising forming a first bump pattern on the first surface of the first wafer prior to the bonding of the second and first wafers.

12. The method of claim 11, further comprising forming at least one opening through the first wafer prior to the bonding of the second and first wafers.

13. The method of claim 12, further comprising baking out the first and second wafers after the bonding of the first and second wafers.

14. The method of claim 13, wherein the baking out the first and second wafers is done within a substantial vacuum.

15. The method of claim 14, further comprising sealing the at least one opening through the first wafer within the substantial vacuum.

16. The method of claim 15, further comprising forming a second bump pattern on a second surface of the first wafer.

17. The method of claim 16, wherein the first and second bump patterns have an anti-reflective characteristic.

18. The method of claim 17, wherein the seal comprises:
a spacer material; and
a malleable layer.

19. The method of claim 18, wherein:
the seal further comprises a layer of gold-like material; and
the malleable layer comprises a solder-like material.

20. A means for integral packaging, comprising:
means for providing a first wafer having a recess about a first perimeter in a first surface of the first wafer; and
means for providing a second wafer bonded to the first wafer.

21. The means of claim 20, wherein the recess is hermetically sealed from an environment external to the

first and second wafers.

22. The means of claim 21, wherein the first surface of the first wafer has a first bump pattern within the first perimeter.

23. The means of claim 22, wherein the first and second wafers comprise a bonding seal along a second perimeter outside of the first perimeter.

24. The means of claim 23, wherein the bonding seal comprises:

a spacer material; and
a malleable layer.

25. The means of claim 24, wherein:

a second surface of the first wafer has a second bump pattern; and
the first and second bump patterns are anti-reflective.

26. An integral package comprising:

a first wafer comprising:

 a seal along a first perimeter on a first surface
 of the first wafer; and

 a trench in the first surface of the first wafer
 along a second perimeter within the first
 perimeter; and

 a second wafer having a first surface bonded to the
 second wafer along the seal.

27. The package of claim 26, wherein the first wafer
further comprises an anti-reflective pattern on the first
surface.

28. The package of claim 27, wherein the first wafer
further comprises at least one vent hole and vent hole
seal.

29. The package of claim 28, wherein the seal comprises a
spacer material.

30. The package of claim 29, wherein the first wafer
further comprises an anti-reflective pattern on a second

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surface.